Product Specification

（Common Application）

Product Name: VGM160080A5W01

Product Code: M03480

Customer
Approved by Customer
Approved Date:

Designed By	Checked By	Approved By	
		R&D	QA

CONTENT

REVISION RECORD

REV.	REVISION DESCRIPTION	REV. DATE	REMARK
Y01	Initial release.	2020-07-13	
Y02	Update Mechanical Drawing Update Module Interface Update Application Circuit Update Package Specification Update Lifetime Modify the company name and update the drawing icon	2021-03-17	Page 5 Page 6 Page 19~23 Page 27 Page 28 All page

1 Application filed

Common Application

2 Overview

VGM160080A5W01 is a gray-scale OLED display module with 160×80 dot matrix. The characteristics of this display module are high brightness, self-emission, high contrast ratio, slim/thin outline, wide viewing angle, wide temperature range, and low power consumption.

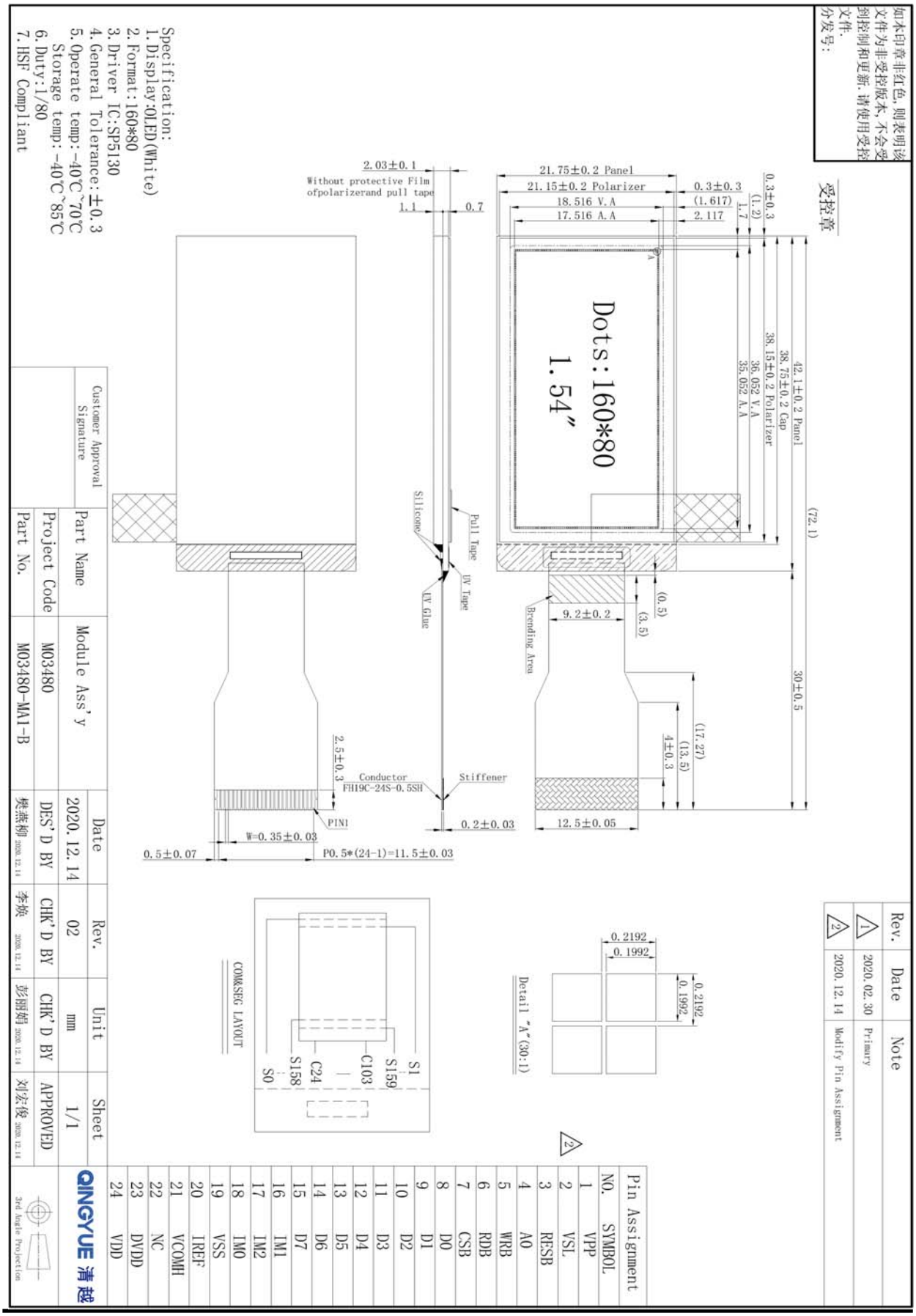
3 Features

- Display Color: White
- Dot Matrix:160×80
- Driver IC: SP5130
- Interface: 8bit 8080,8bit 6800,4/3-wire SPI,I^2C
- Wide range of operating temperature: -40℃ to 70℃
- Wide range of Storage temperature: -40℃ to 85℃

4 Mechanical Data

NO.	ITEM	SPECIFICATION	UNIT
1	Dot Matrix	160(W)×80(H)	-
2	Dot Size	0.1992(W)×0.1992(H)	mm^2
3	Dot Pitch	0.2192(W)×0.2192(H)	mm^2
4	Aperture Rate	83	%
5	Active Area	35.052(W)×17.516(H)	mm^2
6	Panel Size	42.1(W)×21.75(H) ×1.8(T)	mm^3
7	Module Size	72.1(W)×21.75(H) ×2.03(T)	mm^3
8	Diagonal A/A Size	1.54	inch
9	Module Weight	TBD±10%	gram

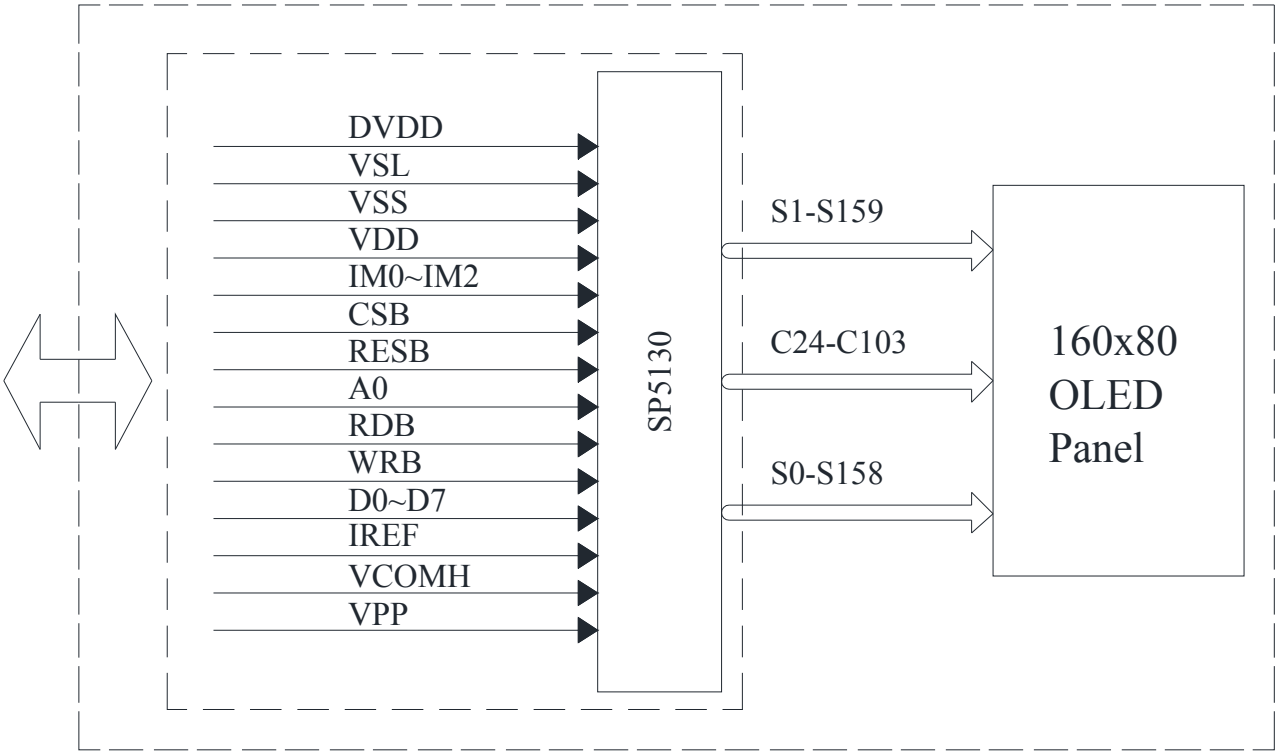
5 Mechanical Drawing



6 Module Interface

<table>
<tr><th>PIN NO.</th><th>PIN NAME</th><th>DESCRIPTION</th></tr>
<tr><td>1</td><td>VPP</td><td>This is the most positive voltage supply pad of the chip, It should be supplied externally.</td></tr>
<tr><td>2</td><td>VSL</td><td>Discharge voltage level pad.</td></tr>
<tr><td>3</td><td>RESB</td><td>This is a reset signal input pad.</td></tr>
<tr><td>4</td><td>A0</td><td>This is the Data/Command control pad that determines whether the data bits are data or a command.
A0 = “H”: the inputs at D0 to D7 are treated as display data.
A0 = “L”: the inputs at D0 to D7 are transferred to the command registers. When in 3-wire interface, this pin is not used, so it must be connected to “L”. In I^2C interface, this pad serves as SA0, must be pull low.</td></tr>
<tr><td>5</td><td>WRB</td><td>This is a MPU interface input pad.
When connected to an 8080 MPU, this is active LOW. This pad connects to the 8080 MPU WR signal. The signals on the data bus are latched at the rising edge of the WR signal. When connected to a 6800 Series MPU: This is the read/write control signal input terminal.
When R /W = “H”: Read. When R/W = “L”: Write.
When in 3-wire.4-wire, this pin is not used, so it must be connected to “L”.</td></tr>
<tr><td>6</td><td>RDB</td><td>This is a MPU interface input pad.
When connected to an 8080 series MPU, it is active LOW. This pad is connected to the RD signal of the 8080 series MPU, and the data bus is in an output status when this signal is “L”. When connected to a 6800 series MPU, this is active HIGH. This is used as an enable clock input of the 6800 series MPU. When in 3-wire.4-wire, this pin is not used, so it must be connected to “L”.</td></tr>
<tr><td>7</td><td>CSB</td><td>This pad is the chip select input. When CS = “L”, then the chip select becomes active, and data/command I/O is enabled.</td></tr>
<tr><td>8~15</td><td>D0~D7</td><td>This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected, then D0 serves as the serial clock input pad (SCL) and D1 serves as the serial data input pad (SI). At this time, D2 to D7 are set to high impedance. When the I^2C interface is selected, then D0 serves as the serial clock input pad (SCL) and D1 serves as the serial data input pad (SDA). At this time, D2 to D7 are set to high impedance.</td></tr>
<tr><td>16</td><td>IM1</td><td rowspan="3">These are the MPU interface mode select pads.
<table>
<tr><th>PIN</th><th>8080</th><th>6800</th><th>4-SPI</th><th>3-SPI</th><th>I^2C</th></tr>
<tr><td>IM0</td><td>0</td><td>1</td><td>0</td><td>0</td><td>0</td></tr>
<tr><td>IM1</td><td>1</td><td>0</td><td>0</td><td>0</td><td>1</td></tr>
<tr><td>IM2</td><td>1</td><td>0</td><td>0</td><td>1</td><td>0</td></tr>
</table></td></tr>
<tr><td>17</td><td>IM2</td></tr>
<tr><td>18</td><td>IM0</td></tr>
<tr><td>19</td><td>VSS</td><td>Ground.</td></tr>
<tr><td>20</td><td>IREF</td><td>This is a segment current reference pad. A resistor should be connected between this pad and GND.</td></tr>
<tr><td>21</td><td>VCOMH</td><td>This is a pad for the voltage output high level for common signals.
A capacitor should be connected between this pad and GND.</td></tr>
<tr><td>22</td><td>NC</td><td>No connection.</td></tr>
<tr><td>23</td><td>DVDD</td><td>This pin is for regulator circuit.
A capacitor should be connected between this pad and GND</td></tr>
<tr><td>24</td><td>VDD</td><td>1.65V– 3.6V Power supply for logic and input/output</td></tr>
</table>

7 Function Block Diagram



8 Absolute Maximum Ratings

ITEM	SYMBOL	MIN	MAX	UNIT	REMARK
Supply Voltage	VDD	-0.3	3.6	V	IC maximum rating
	VPP	-0.3	18	V	IC maximum rating
Operating Temp.	Top	-40	+70	℃	-
Storage Temp	Tstg	-40	+85	℃	-

Note (1): All of the voltages are on the basis of "GND = 0V".

Note (2): Permanent breakage of module may occur if the module is used beyond the maximum rating. The module can be normal operated under the conditions according to Section 9 "Electrical Characteristics". Malfunctioning of the module may occur and the reliability of the module may deteriorate if the module is used beyond the conditions.

9 Electrical Characteristics

9.1 DC Electrical Characteristics

ITEM	SYMBOL	TEST CONDITION	MIN	TYPE	MAX	UNIT
Logic Supply Voltage	VDD	22±3°C, 55±15%R.H	1.65	3.3	3.6	V
OLED Driver Supply Voltage (Supplied by external)	VPP	22±3°C, 55±15%R.H	11.5	12	12.5	V
High-level Input Voltage	V_{IH}	A0, D0~D7, RDB, WRB , CSB , IM1~2 and RESB .	0.8×VDD	-	VDD	V
Low-level Input Voltage	V_{IL}	A0, D0~D7, RDB, WRB , CSB , IM1~2 and RESB .	VSS	-	0.2×VDD	V
High-level Output Voltage	V_{OH}	I_{OH} = -0.5mA (D0~D7).	0.8×VDD	-	VDD	V
Low-level Output Voltage	V_{OL}	I_{OL} = -0.5mA (D0~D7).	VSS	-	0.2×VDD	V

Note: The VPP, VDD input must be kept in a stable value; ripple and noise are not allowed.

9.2 Electro-optical Characteristics

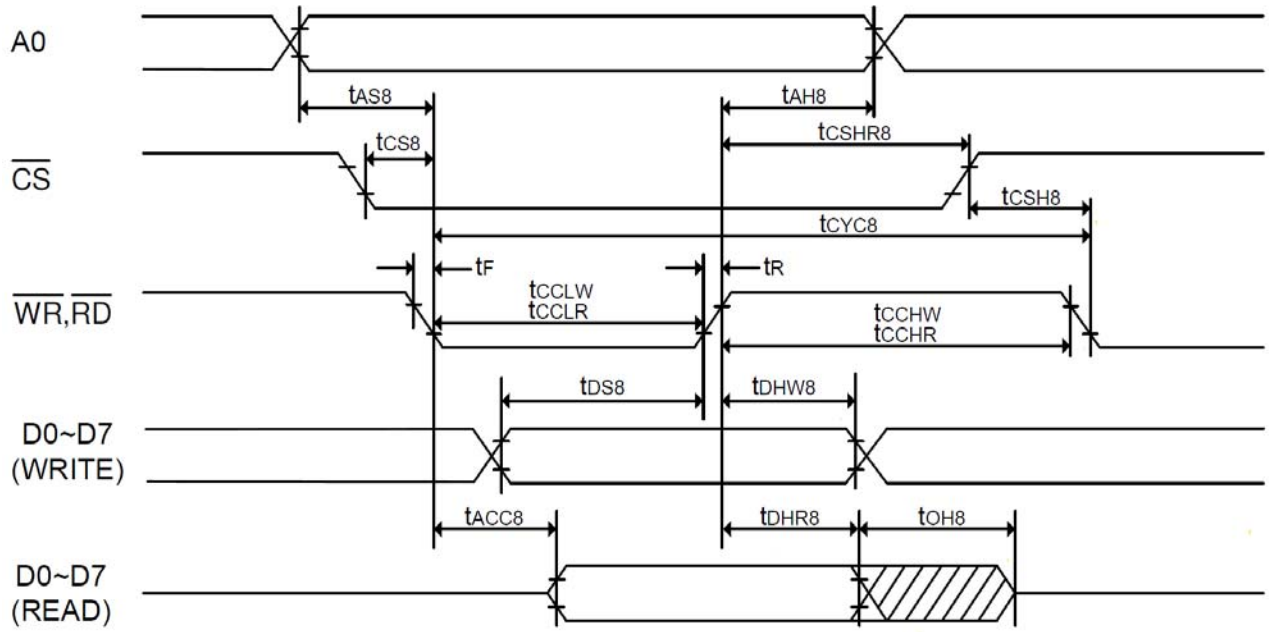
ITEM	SYMBOL	TEST CONDITION	MIN	TYPE	MAX	UNIT
Normal Mode Brightness (With polarizer)	L_{br}	All pixels ON (1) (VPP Supplied by external)	120	150	-	cd/m^2
VPP Sleep mode Current	IPP,SLEEP	TA = +25°C, VPP = 15V (External) Display OFF, No panel attached	-	-	10	uA
VDD Sleep mode Current	IDD,SLEEP	During sleep, TA = +25°C, VDD = 1.8V, Sram power off (CMD DAH bit6 & bit7 = 0)	-	-	10	uA
		During sleep, TA = +25°C, VDD = 2~3.6V, Sram power off (CMD DAH bit6 & bit7 = 0)	-	-	120	uA
Normal Mode Power Consumption	Pt	All pixels ON(1) (VPP Supplied by external)	-	552	720	mW
C.I.E(White)	(X)	x,y(CIE1931)	0.26	0.30	0.34	-
	(Y)		0.29	0.33	0.37	
Dark Room Contrast	CR		≥10000:1			
Response Time	-		-	10	-	μs
View Angle	-	-	≥160	-	-	Degree

Note(1): Normal Mode test conditions are as follows:

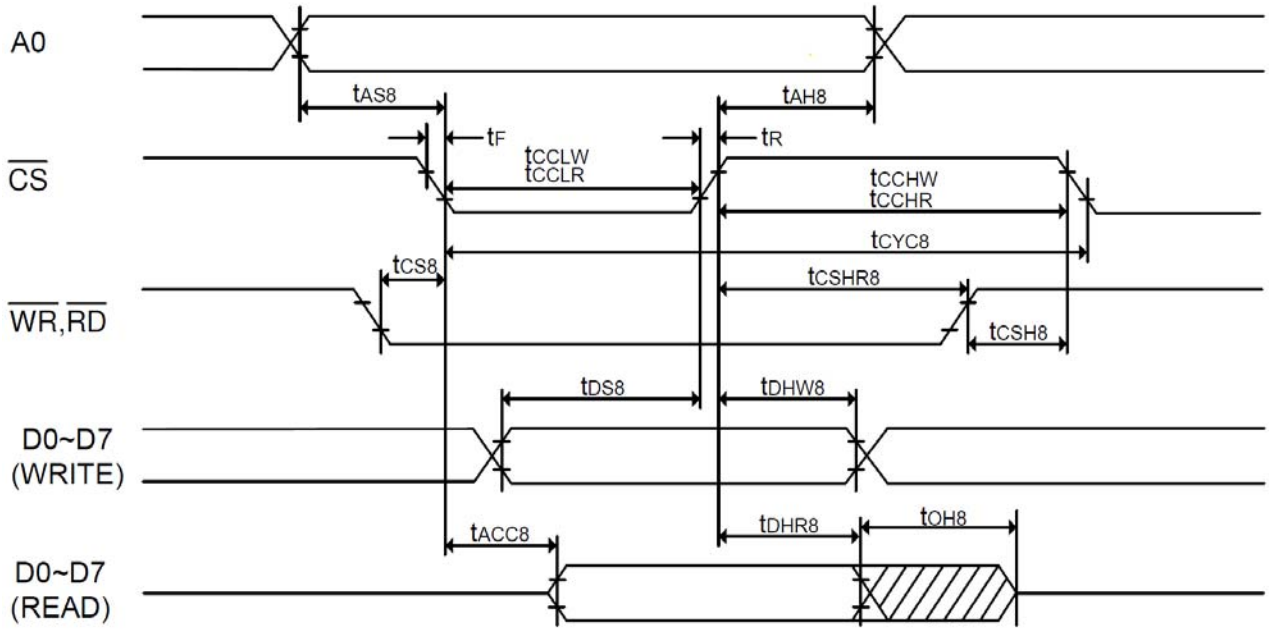
- Driving voltage: 12V
- Contrast setting: 0xFF
- Frame rate: 104HZ
- Duty setting: 1/80

9.3 AC Electrical Characteristics

(1) System buses Read/Write characteristics (For the 8080)



8080-series parallel interface cycle (Form1)

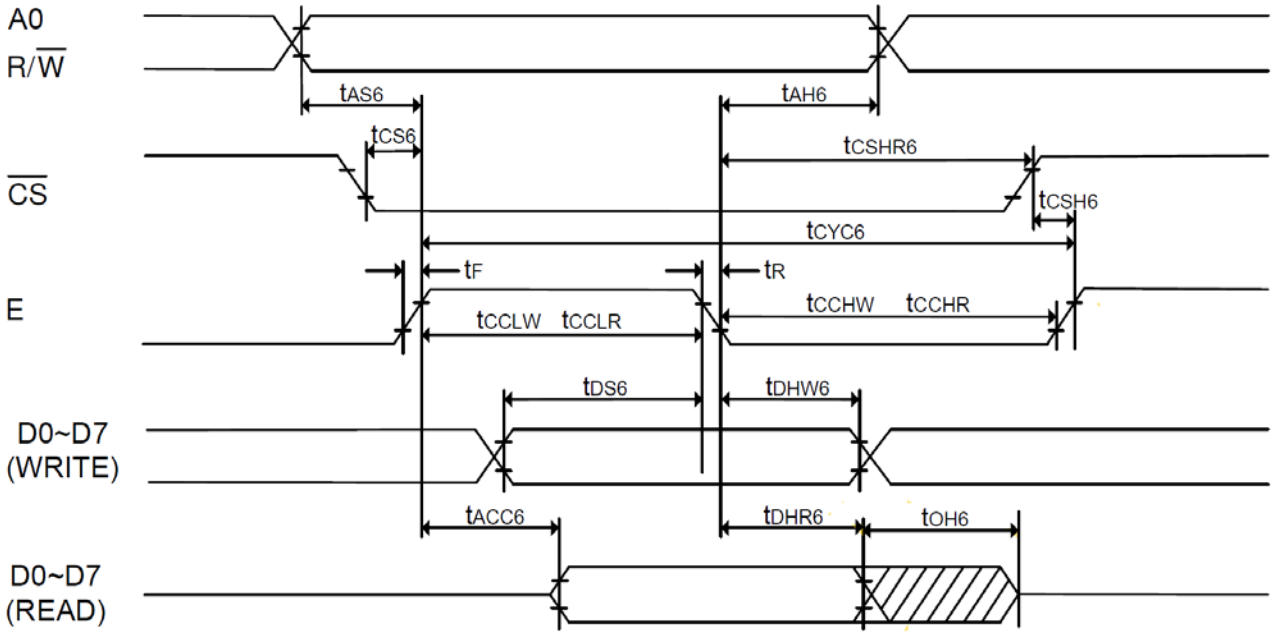


8080-series parallel interface cycle (Form2)

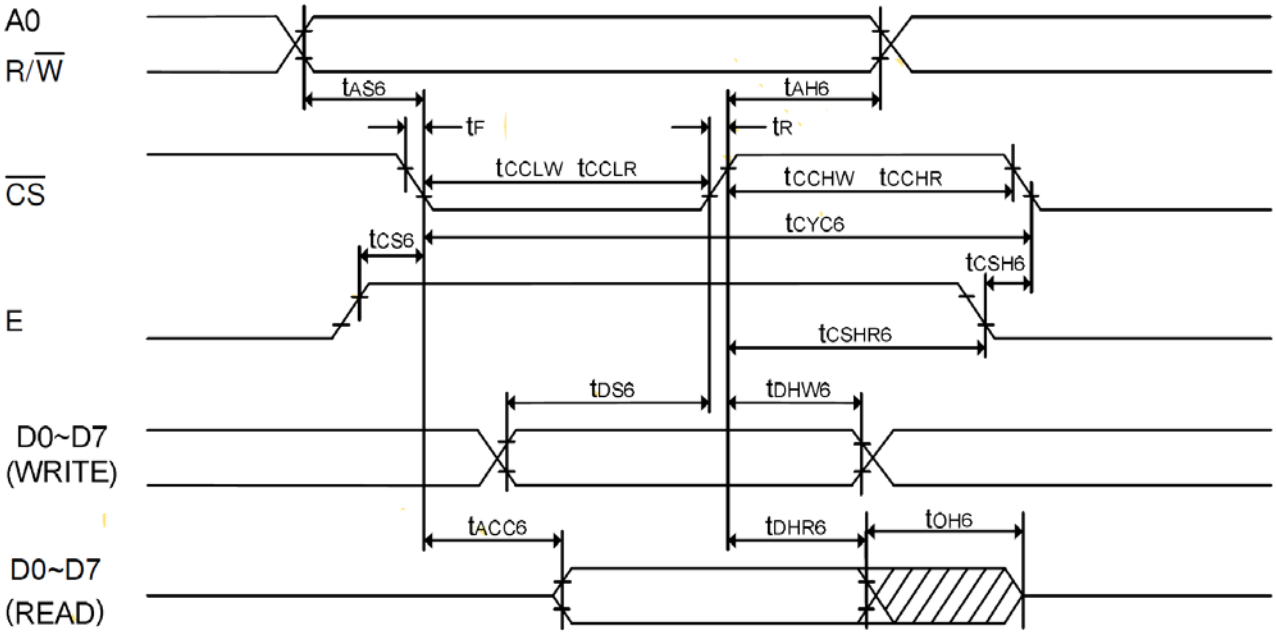
(V_{DD} = 1.65 – 3.6V, T_A = +25°C)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Condition
t_{CYC8}	System cycle time	300	-	-	ns	
t_{AS8}	Address setup time	0	-	-	ns	
t_{AH8}	Address hold time	0	-	-	ns	
t_{DS8}	Data setup time	40	-	-	ns	
t_{DHW8}	Write Data hold time	10	-	-	ns	
t_{DHR8}	Read Data hold time	10	-	-	ns	
t_{OH8}	Output disable time	-	-	70	ns	C_L = 100pF
t_{ACC8}	$\overline{RD}$ access time	-	-	140	ns	C_L = 100pF
t_{CCLW}	Control L pulse width (WR)	150	-	-	ns	
t_{CCLR}	Control L pulse width (RD)	150	-	-	ns	
t_{CCHW}	Control H pulse width (WR)	150	-	-	ns	
t_{CCHR}	Control H pulse width (RD)	150	-	-	ns	
t_R	Rise time	-	-	15	ns	
t_F	Fall time	-	-	15	ns	
t_{CS8}	Chip select setup time	0	-	-	ns	
t_{CSH8}	Chip select hold time	20	-	-	ns	
t_{CSHR8}	Chip select hold time to read signal	20	-	-	ns	

(2) System buses Read/Write characteristics (For the 6800)



6800-series parallel interface cycle (Form1)

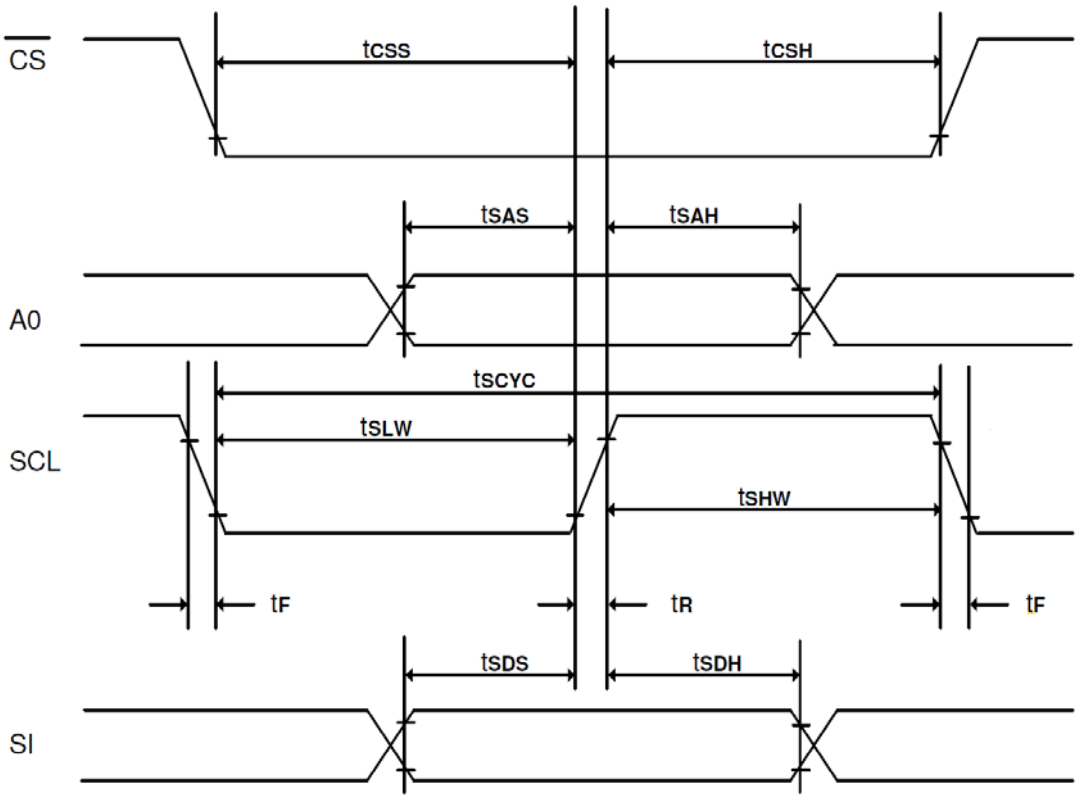


6800-series parallel interface cycle (Form2)

(V_{DD} = 1.65 – 3.6V, T_A = +25°C)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Condition
t_{CYC6}	System cycle time	300	-	-	ns	
t_{AS6}	Address setup time	0	-	-	ns	
t_{AH6}	Address hold time	0	-	-	ns	
t_{DS6}	Data setup time	40	-	-	ns	
t_{DHW6}	Write Data hold time	10	-	-	ns	
t_{DHR6}	Read Data hold time	10	-	-	ns	
t_{OH6}	Output disable time	-	-	70	ns	C_L = 100pF
t_{ACC6}	Access time	-	-	140	ns	C_L = 100pF
t_{EWHW}	Enable H pulse width (Write)	150	-	-	ns	
t_{EWHR}	Enable H pulse width (Read)	150	-	-	ns	
t_{EWLW}	Enable L pulse width (Write)	150	-	-	ns	
t_{EWLR}	Enable L pulse width (Read)	150	-	-	ns	
t_R	Rise time	-	-	15	ns	
t_F	Fall time	-	-	15	ns	
t_{CS6}	Chip select setup time	0	-	-	ns	
t_{CSH6}	Chip select hold time	20	-	-	ns	
t_{CSHR6}	Chip select hold time to read signal	20	-	-	ns	

(3) System buses Write characteristics (For 4 wire SPI)

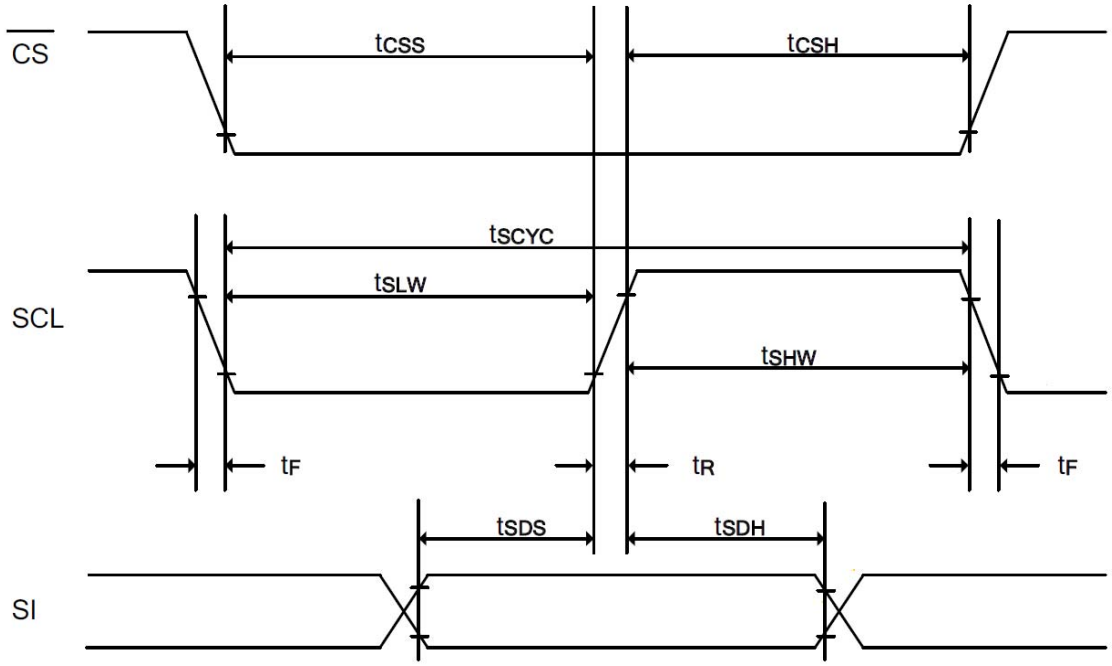


(V_{DD} = 1.65 – 3.6V, T_A = +25°C)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Condition
tSCYC	Serial clock cycle	66	-	-	ns	
tSAS	Address setup time	30	-	-	ns	
tSAH	Address hold time	30	-	-	ns	
tSDS	Data setup time	20	-	-	ns	
tSDH	Data hold time	20	-	-	ns	
tCSS	$\overline{CS}$ setup time	45	-	-	ns	
tCSH	$\overline{CS}$ hold time time	12	-	-	ns	
tSHW	Serial clock H pulse width	20	-	-	ns	
tSLW	Serial clock L pulse width	20	-	-	ns	
tR	Rise time	-	-	3	ns	
tF	Fall time	-	-	3	ns	

Note. When read cmd needed, it must delay 1/2 tSCYC time after write cmd.

(4) System buses Write characteristics (For 3-SPI)

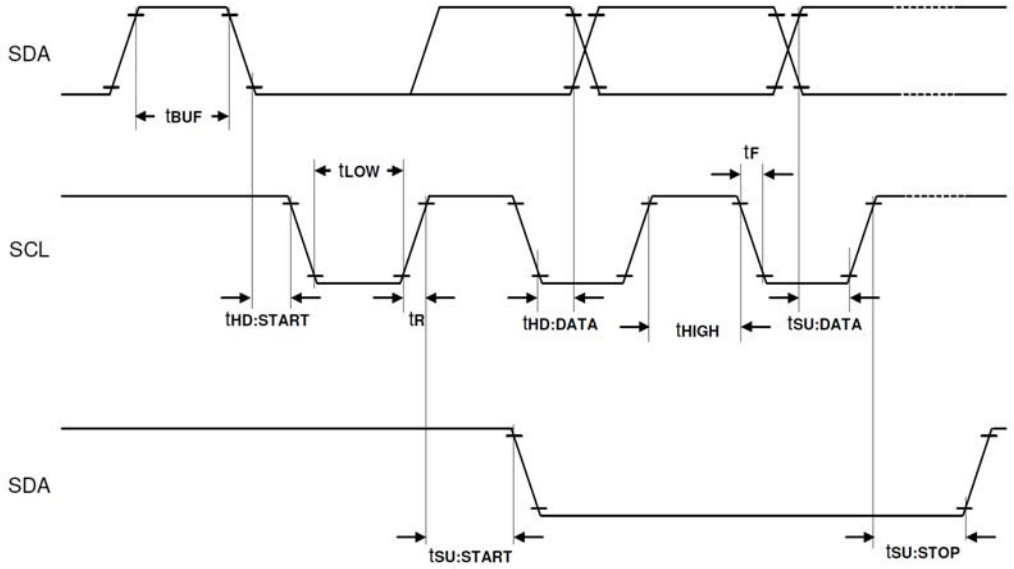


(V_{DD} = 1.65 – 3.6V, T_A = +25°C)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Condition
t_{SCYC}	Serial clock cycle	66	-	-	ns	
t_{SDS}	Data setup time	20	-	-	ns	
t_{SDH}	Data hold time	20	-	-	ns	
t_{CSS}	$\overline{CS}$ setup time	45	-	-	ns	
t_{CSH}	$\overline{CS}$ hold time time	12	-	-	ns	
t_{SHW}	Serial clock H pulse width	20	-	-	ns	
t_{SLW}	Serial clock L pulse width	20	-	-	ns	
t_R	Rise time	-	-	3	ns	
t_F	Fall time	-	-	3	ns	

Note. When read cmd needed, it must delay 1/2 t_{SCYC} time after write cmd.

(5) System buses Write characteristics (For I^2C)



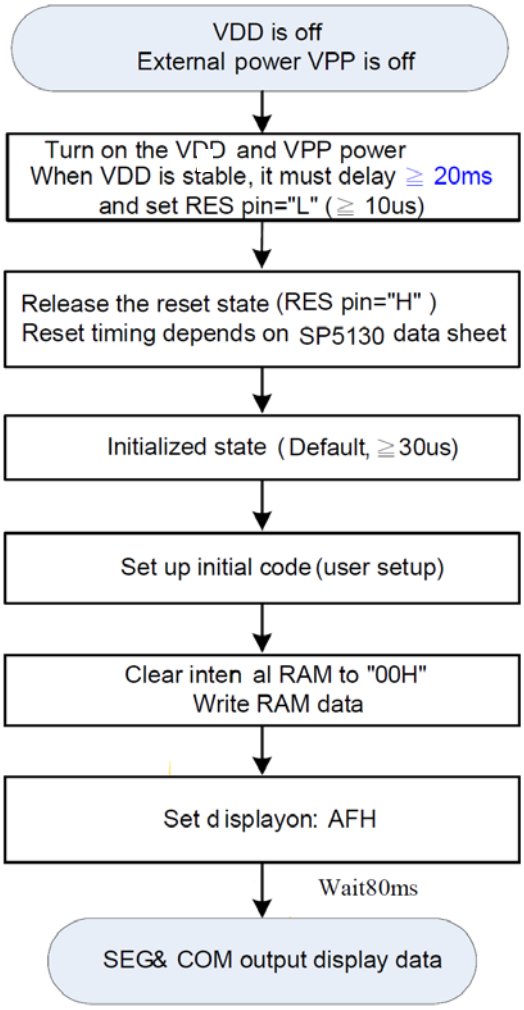
(V_{DD} = 1.65 – 3.6V, TA = +25°C)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Condition
fSCL	SCL clock frequency	DC	-	400	kHz	
TLOW	SCL clock Low pulse width	1.3	-	-	us	
THIGH	SCL clock H pulse width	0.6	-	-	us	
TSU:DATA	data setup time	100	-	-	ns	
THD:DATA	data hold time	0	-	0.9	us	
TR	SCL、SDA rise time	20+0.1Cb	-	300	ns	
TF	SCL SDA fall time	20+0.1Cb	-	300	ns	
	Capacity load on each bus	-	-	400	pF	
TSU:START	Setup timefor re-START	0.6	-	-	us	
THD:START	START Hold time	0.6	-	-	us	
TSU:STOP	Setup time for STOP	0.6	-	-	us	
TBUF	Bus free times between STOP and START condition	1.3	-	-	us	

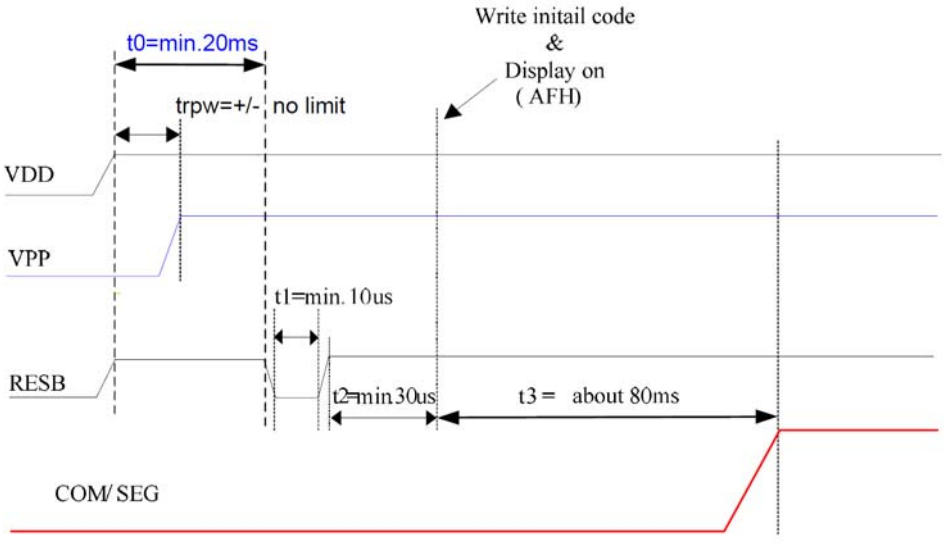
10 Functional Specification and Application Circuit

10.1 Power ON and Power OFF Sequence

9. 1. 1 External power is being used immediately after turning on the power

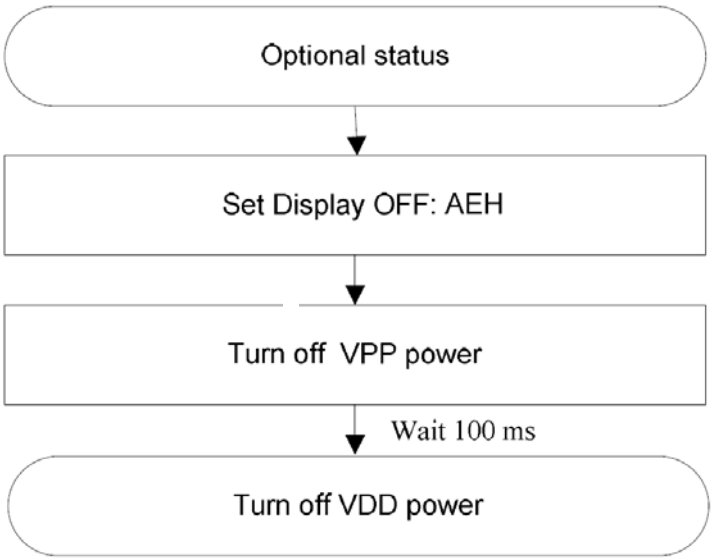


Power on Sequence:

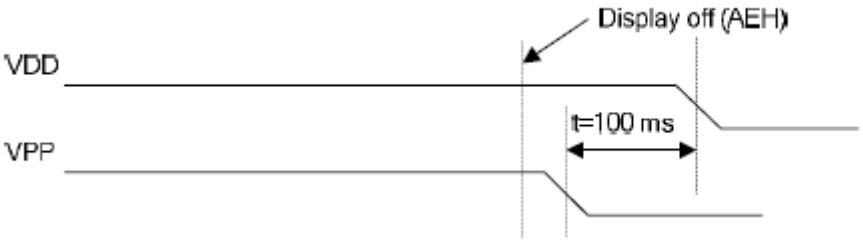


Note. It is necessary to do hardware reset in power on sequence.

9. 1. 2 Power OFF



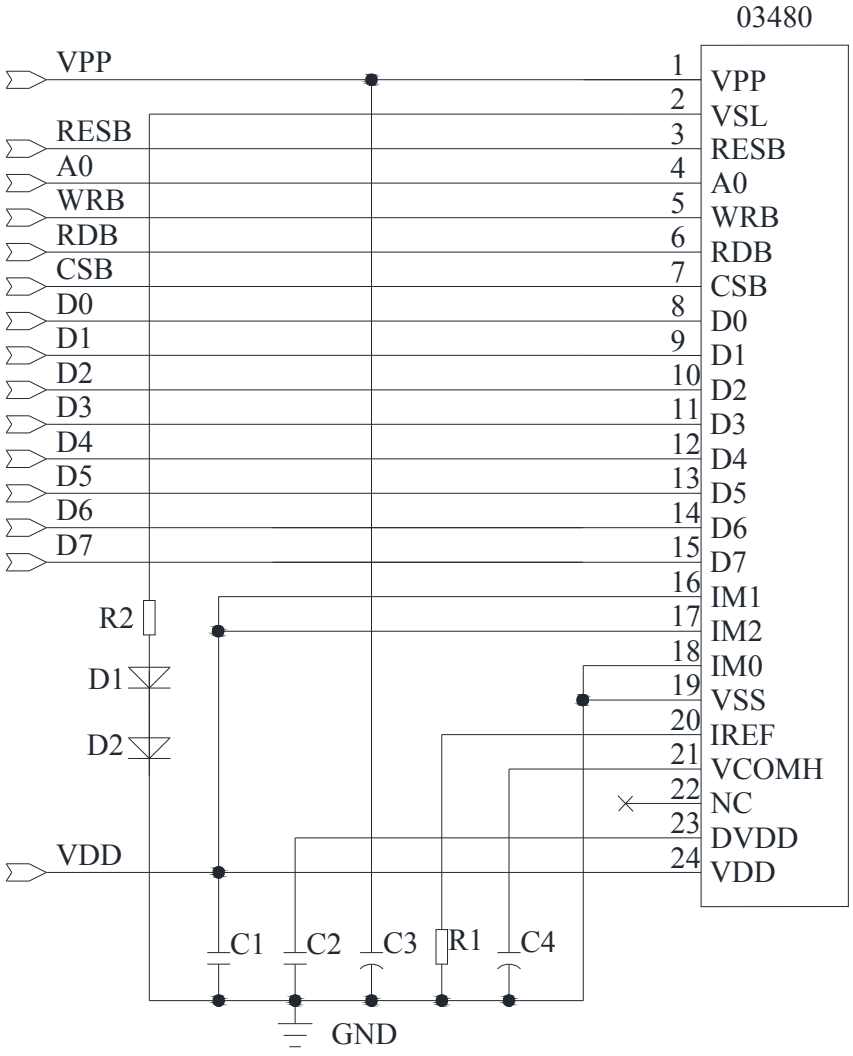
Power on Sequence:



Note: There will be no damages to the display module if the power sequences are not met. User cannot read/write ram before display off command(AEH) and after display off command(AEH) about 100us.

10.2 Application Circuit

1).The configuration for 8080 interface mode, external VPP is shown in the following diagram



Pin connected to MCU interface: CSB, RESB, A0, WRB, RDB, D0~D7

Recommended components

C1, C2: 1uF-0603-X7R±10%.RoHS

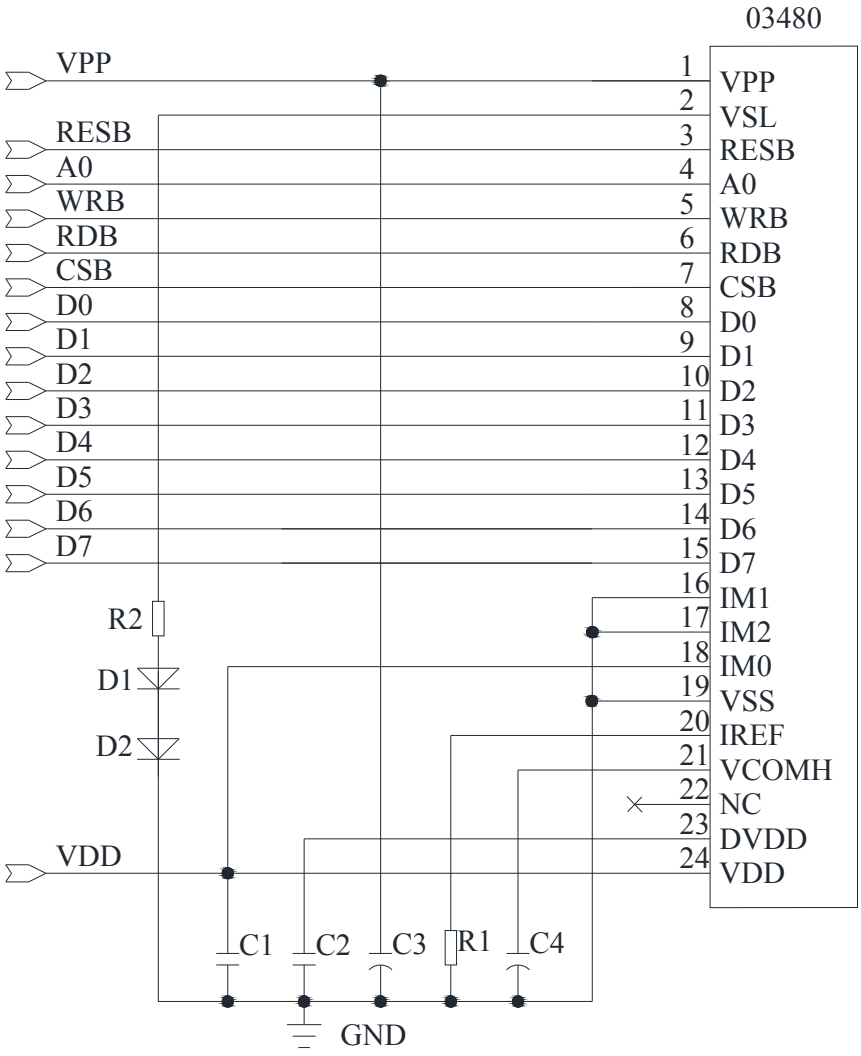
C3, C4: 4.7μF/25V.RoHS (Tantalum Capacitors)

R1: 0603 1/10W +/-5% 390Kohm.RoHS

R2: 0603 1/10W +/-5% 0ohm.RoHS

D1, D2: Vth=0.7V, 1N4148.RoHS

2).The configuration for 6800 interface mode, external VPP is shown in the following diagram



Pin connected to MCU interface: CSB, RESB, A0, WRB, RDB, D0~D7

Recommended components

C1, C2: 1uF-0603-X7R±10%.RoHS

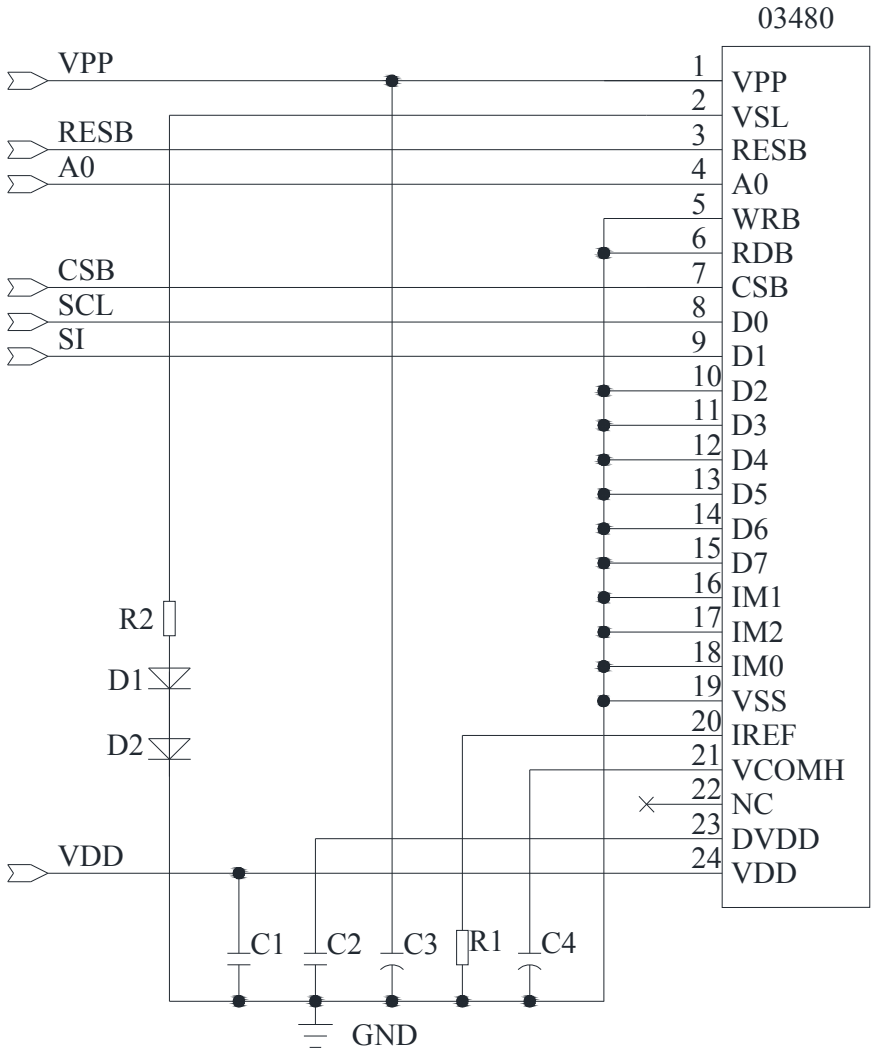
C3, C4: 4.7μF/25V.RoHS (Tantalum Capacitors)

R1: 0603 1/10W +/-5% 390Kohm.RoHS

R2: 0603 1/10W +/-5% 0ohm.RoHS

D1, D2: Vth=0.7V, 1N4148.RoHS

3).The configuration for 4-SPI interface mode, external VPP is shown in the following diagram



Pin connected to MCU interface: CSB, RESB, A0, SCL, SI

Recommended components

C1, C2: 1uF-0603-X7R±10%.RoHS

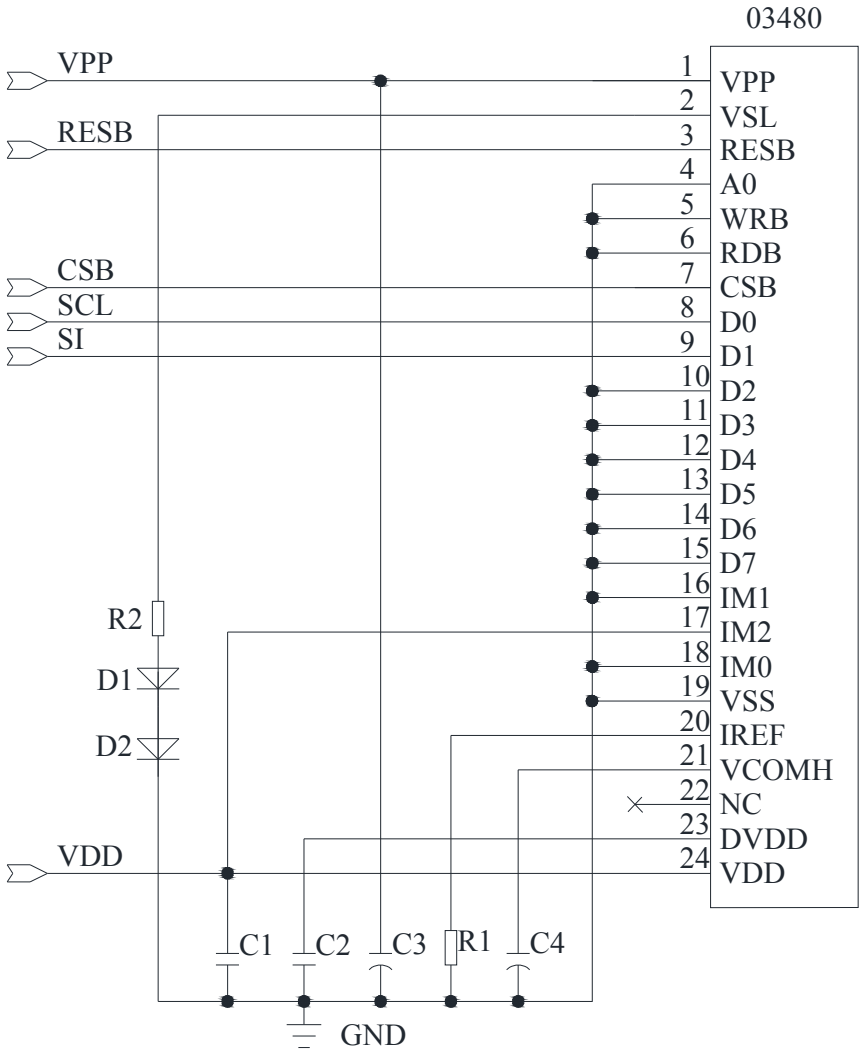
C3, C4: 4.7μF/25V.RoHS (Tantalum Capacitors)

R1: 0603 1/10W +/-5% 390Kohm.RoHS

R2: 0603 1/10W +/-5% 0ohm.RoHS

D1, D2: Vth=0.7V, 1N4148.RoHS

4).The configuration for 3-SPI interface mode, external VPP is shown in the following diagram



Pin connected to MCU interface: CSB, RESB, SCL, SI.

Recommended components

C1, C2: 1uF-0603-X7R±10%.RoHS

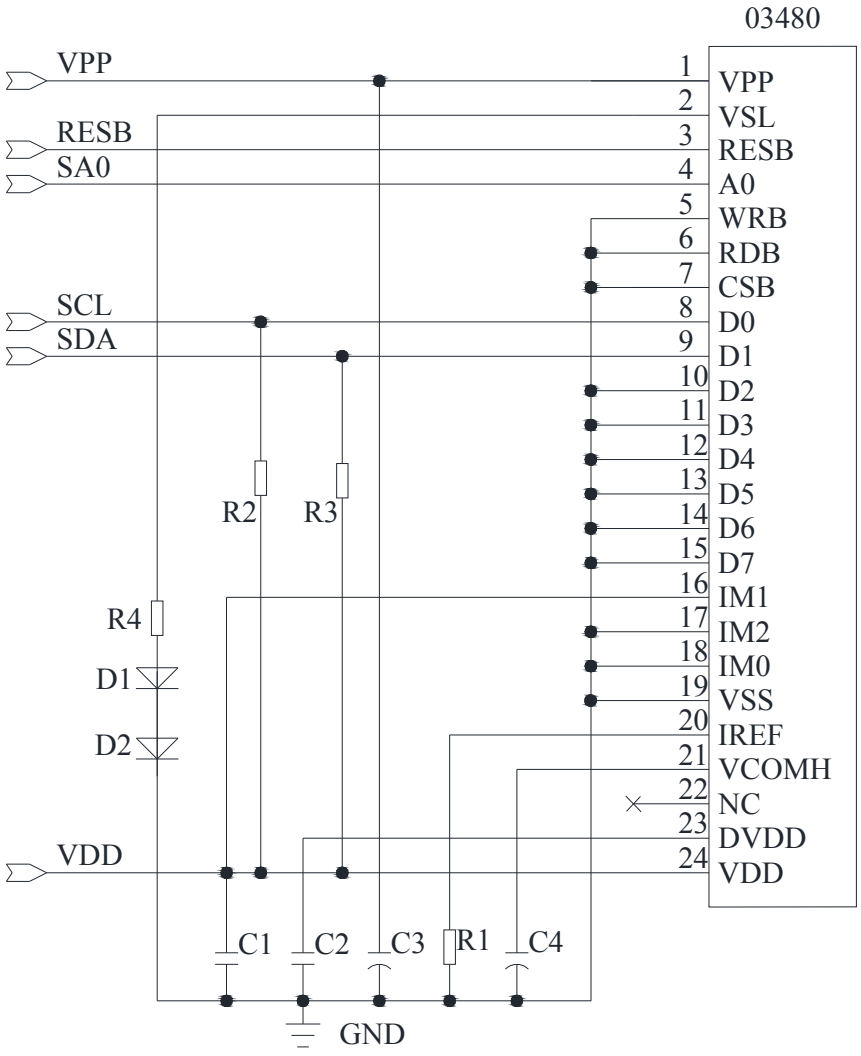
C3, C4: 4.7μF/25V.RoHS (Tantalum Capacitors)

R1: 0603 1/10W +/-5% 390Kohm.RoHS

R2: 0603 1/10W +/-5% 0ohm.RoHS

D1, D2: Vth=0.7V, 1N4148.RoHS

5).The configuration for I^2C interface mode, external VPP is shown in the following diagram



Pin connected to MCU interface: RESB, SA0, SCL, SDA

SA0	I^2C Slave address
0	0x78
1	0x7a

Recommended components

C1, C2: 1uF-0603-X7R±10%.RoHS

C3, C4: 4.7μF/25V.RoHS (Tantalum Capacitors)

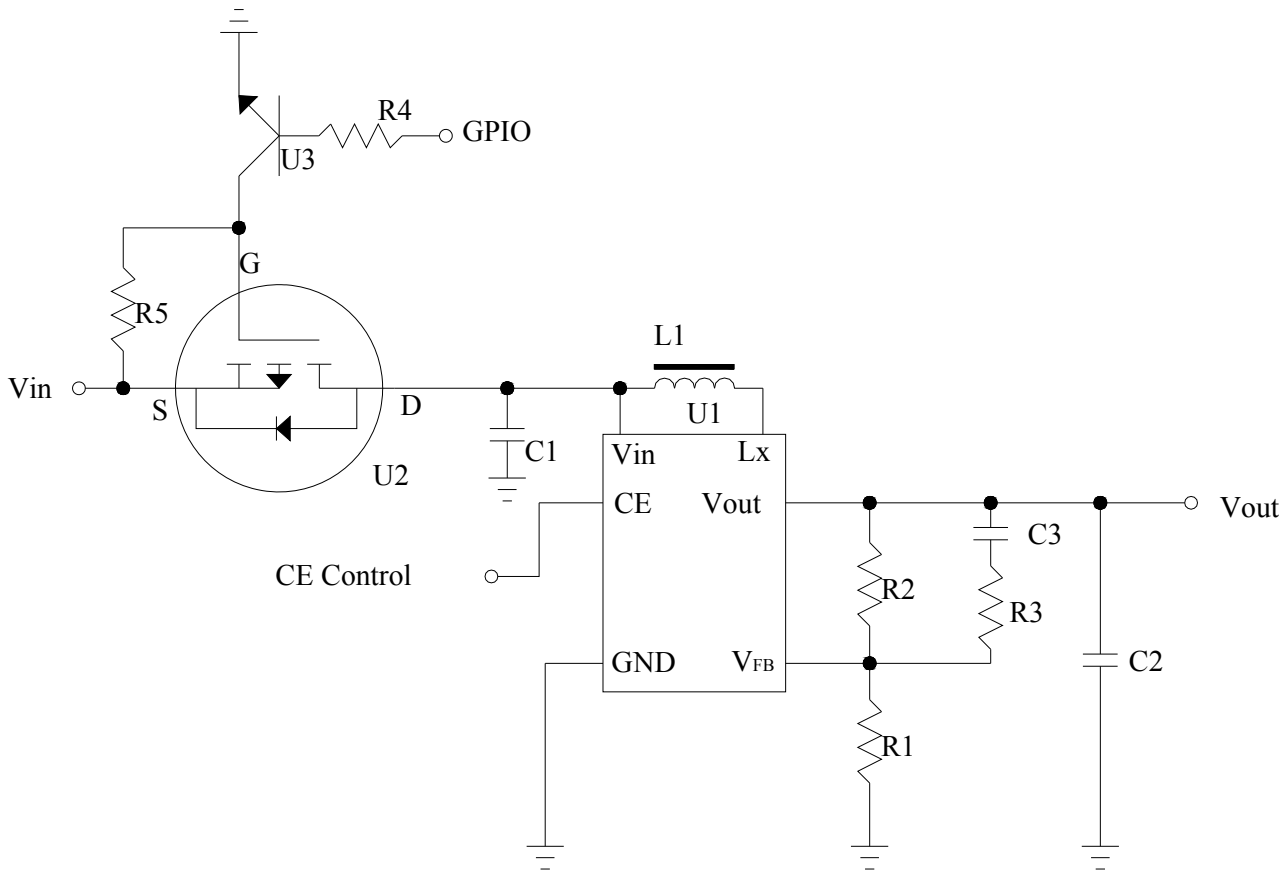
R1: 0603 1/10W +/-5% 390Kohm.RoHS

R2, R3: 0603 1/10W +/-5% 10Kohm.RoHS

R4: 0603 1/10W +/-5% 0ohm.RoHS

D1, D2: Vth=0.7V, 1N4148.RoHS

10.3 External DC-DC application circuit



Recommend component

The C1	: 1 uF-0603-X7R±10%.RoHS
The C2	: 1 uF-0603-X7R±10%.RoHS
The C3	: 220pF-0603-X7R±10%.RoHS
The R1	: 0603 1/10W +/-5% 10Kohm.RoHS
The R2	: 0603 1/10W +/-5% 110Kohm.RoHS
The R3	: 0603 1/10W +/-5% 2Kohm.RoHS
The R4	: 0603 1/10W +/-5% 1Kohm.RoHS
The R5	: 0603 1/10W +/-5% 10Kohm.RoHS
The L1	: 22uH
The U1	: R1200
The U2	: FDN338P
The U3	: 8050

10.4 Display Control Instruction

Refer to SP5130 IC Specification.

10.5 Recommended Software Initialization

In order to ensure the reliability and stability of the module, the module must initialized use the following code, Malfunctioning of the module may occur and the reliability of the module may deteriorate if the module is used beyond the initialize code.

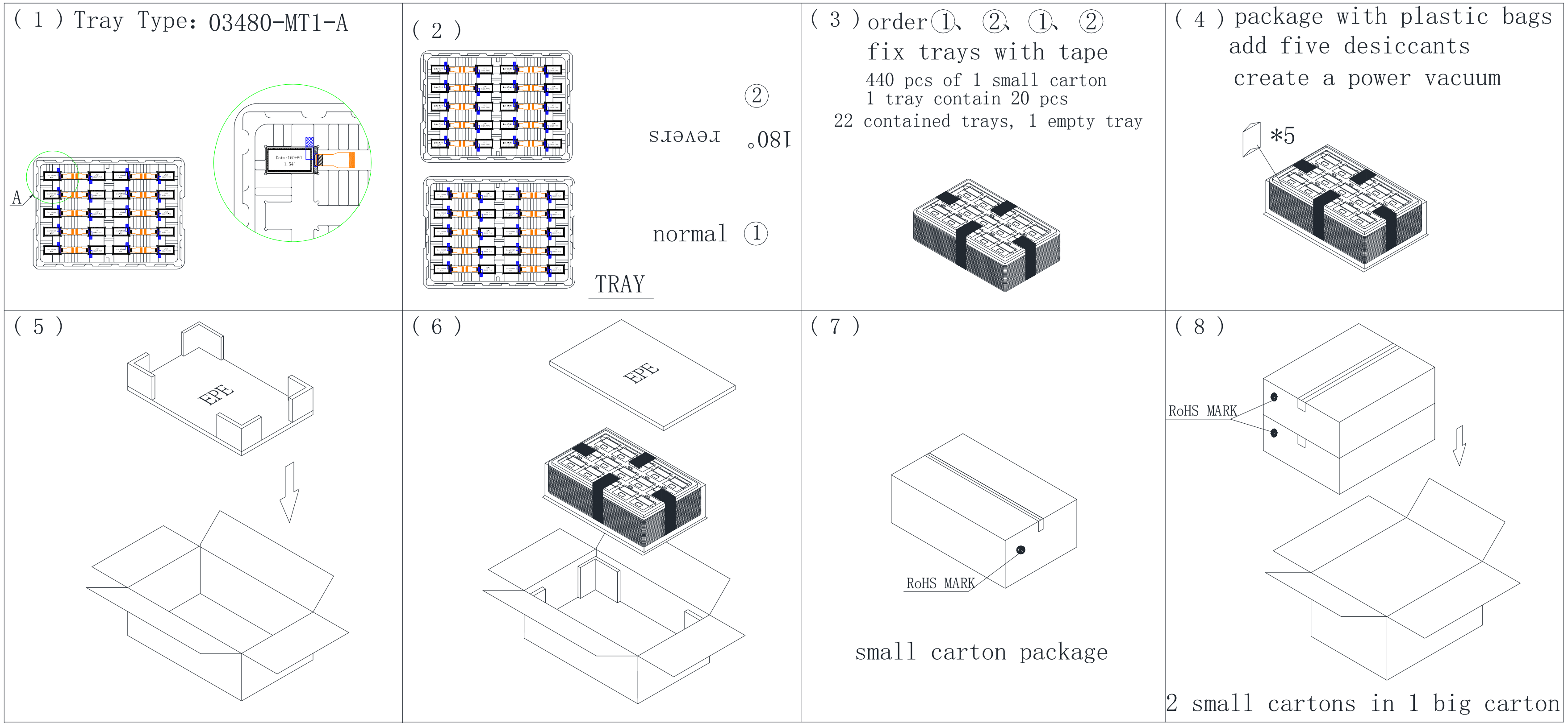
```
void init_program()
  {
   Write_Command(0xAE);        //Set Display Off
   Write_Command(0xB0);        //Set Row Start Address of Display RAM
   Write_Command(0x00);
   Write_Command(0x21);        //Set Column Start and End Address
   Write_Command(0x00);
   Write_Command(0x4F);
   Write_Command(0x22);        //Set Row Start and End Address
   Write_Command(0x00);
   Write_Command(0x4F);
   Write_Command(0x20);        //Set Memory addressing mode
   Write_Command(0x00);        //Horizontal addressing mode
   Write_Command(0x81);        //Set Contrast Control Register
   Write_Command(0xFF);
   Write_Command(0xAD);        //External or internal IREF Set
   Write_Command(0x00);        //External resistor is selected
   Write_Command(0xA0);        //Set Segment Re-map
   Write_Command(0xA4);        //Set Entire Display OFF/ON
   Write_Command(0xA6);       //Set Normal/Reverse Display
   Write_Command(0xA8);        //Set Multiplex Ration
   Write_Command(0x4F);
   Write_Command(0xC8);        //Set Common Output Scan Direction Com0→Com(N-1)
   Write_Command(0xB8);        //gamma 2.2
   Write_Command(0x00);        //0
   Write_Command(0x03);        //1
   Write_Command(0x07);        //2
   Write_Command(0x0B);        //3
   Write_Command(0x0F);        //4
   Write_Command(0x13);        //5
   Write_Command(0x17);        //6
   Write_Command(0x1B);        //7
```

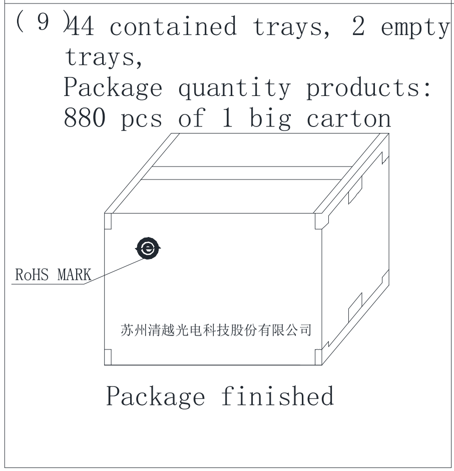
```
    Write_Command(0x1F);          //8
    Write_Command(0x23);          //9
    Write_Command(0x27);          //10
    Write_Command(0x2C);          //11
    Write_Command(0x31);          //12
    Write_Command(0x36);          //13
    Write_Command(0x3B);          //14
    Write_Command(0X3F);          //15
    Write_Command(0xD3);          //Set Display Offset
    Write_Command(0x28);          //Com start 0xA0-0x67
    Write_Command(0xD5);          //Set Display Clock Divide Ratio/Oscillator Frequency
    Write_Command(0x32);
    Write_Command(0xD9);          //Set Dis-charge/Pre-charge Period
    Write_Command(0x01);
    Write_Command(0x01);
    Write_Command(0xD0);
    Write_Command(0x0E);
    Write_Command(0x98);          //pre-charge的驱动能力调节，勿变动
    Write_Command(0x00);
    Write_Command(0x9C);
    Write_Command(0x00);
    Write_Command(0xDA);          //SEG Pads Hardware Configuration Mode Set
    Write_Command(0xC0);
    Write_Command(0xDB);          //Set VCOM Deselect Level
    Write_Command(0x30);          //0.7*VCC
    Write_Command(0xDC);          //Set Row non-overlap/SEG Hiz Period
    Write_Command(0x00);
    Write_Command(0x00);
    Clear_Screen();
    Write_Command(0xAF);          //Set Display On
}
```

11 Package Specification

Controlled Seal

Packing Process(1)~(9)





NOTE:1、The inner carton and master carton must be sealed with adhesive tape.

2、Fill up the gap with empty EPE.

3、If the customer has special needs with the RoHS making, the inner carton and master carton need adhesive new RoHS marking at ⓔ .

4、Packaging materials are not recommended for recycling.

12 Reliability

12.1 Reliability Test

NO.	ITEM	CONDITION	QUANTITY
1	High Temperature (Non-operation)	85℃,240hrs	4
2	Low Temperature (Non-operation)	-40℃,240hrs	4
3	High Temperature (Operation)	70℃,240hrs	4
4	Low Temperature (Operation)	-40℃,240hrs	4
5	High Temperature / High Humidity (Operation)	60℃,90%RH,240hrs	4
6	Thermal shock (Non-operation)	-40 ℃ ~85 ℃ (-40 ℃ /30min;transit/5min;85 ℃ /30min;transit/5min) 1cycle: 70min,30cycles	4
7	ESD Air discharge (Non-operation)	±8kV, Test 9 point; Each point discharge 10 times. Time interval is not less than 1 second.	4

Test and measurement conditions

1. All measurements shall not be started until the specimens attain to temperature stability, the stable time is at least 15 minutes.
2. The degradation of polarizer is ignored for item 5.
3. The tolerance of temperature is ±3℃, and the tolerance of relative humidity is ±5%.

Evaluation criteria

1. The function test is OK, High temperature storage tests ignore polarizer changes.
2. No observable defects.
3. Luminance:≥50% of initial value.
4. Current consumption: within ± 50% of initial value.

12.2 Lifetime

End of lifetime is specified as 50% of initial brightness and the test pattern at operating condition is 50% alternating checkerboard.

ITEM	MIN	MAX	UNIT	CONDITION
Operation Life Time	10,000	-	hrs	150 cd/m^2, 50% alternating checkerboard, 22±3°C, 55±15% RH

12.3 Failure Check Standard

After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 22±3°C; 55±15% RH.

13 Illustration of OLED Product Name

□ □ □ □□□□□□ □□ □ □□

Flow No. :

01~99

Display Color :

R—red

G—green

B—blue

Y—yellow

M—amber

W—white

A—area color

F—full color

Panel Flow No. :

A0~A9, B0~B9…Z0~Z9

Display Format :

Graphic—columns and rows

Character—characters and line number

Segment—segment number

Mixed—pixel number

Product Type :

P—panel

M—module

Display Type :

G—graphic

C—character

S—segment

I—Icon

M—mixed

Company :

V—QingYue

14 Outgoing Quality Control Specifications

14.1 Sampling Method

(1) GB/T 2828.1/ISO2859-1: inspection level Ⅱ, normal inspection, single sample inspection

(2) AQL: Major 0.65; Minor 1.0

14.2 Inspection Conditions

The environmental conditions for test and measurement are performed as follows.

Temperature: 22±3°C

Humidity: 55±15%R.H

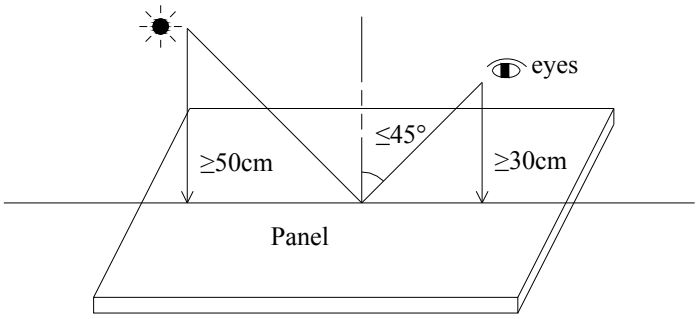
Fluorescent Lamp: 30W

Distance between the Panel & Lamp: ≥50cm

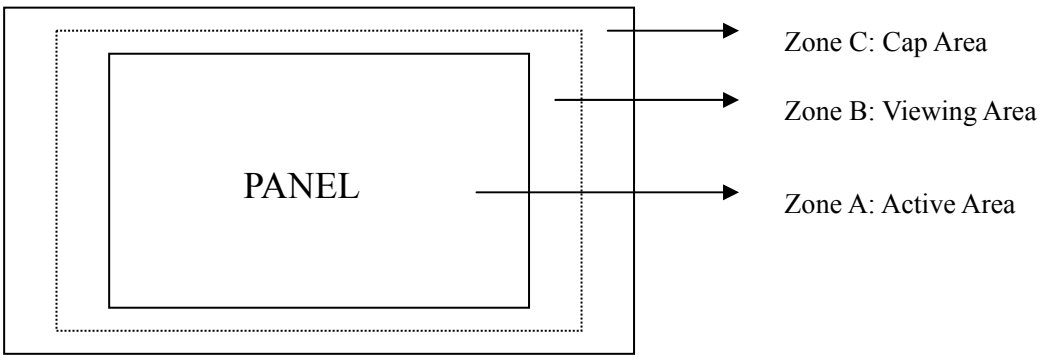
Distance between the Panel & Eyes: ≥30cm

Viewing angle from the vertical in each direction: ≤45°

(See the sketch below)

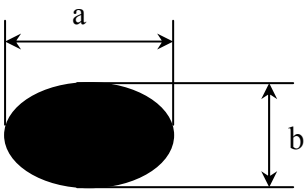


14.3 Quality Assurance Zones

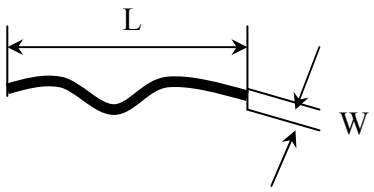


14.4 Inspection Standard

Definition of Φ&L&W (Unit: mm)

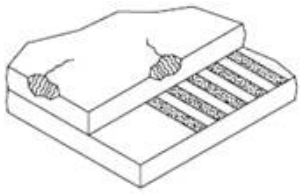
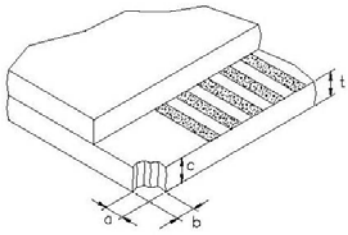
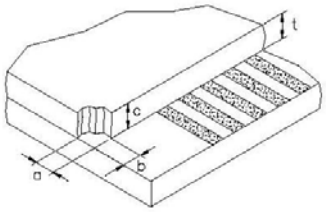
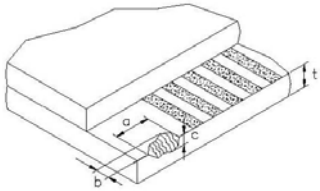
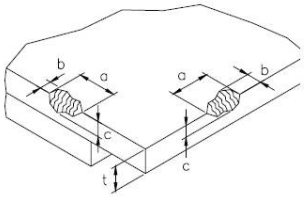
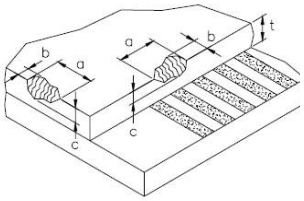


Φ=(a+b)/2



Ⅰ. Appearance Defects

<table>
<tr><th>NO.</th><th>ITEM</th><th>CRITERIA</th><th>CLASSIFICATION</th></tr>
<tr><td>1</td><td>Polarizer Black or White spot, Dirty spot, Foreign matter, Dent on the polarizer</td><td>
<table>
<tr><td rowspan="2">Average Diameter (mm)</td><td colspan="2">Acceptable Number</td></tr>
<tr><td>Zone A,B</td><td>Zone C</td></tr>
<tr><td>Φ≤0.15</td><td>Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.15<Φ≤0.30</td><td>3</td></tr>
<tr><td>Φ>0.30</td><td>0</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>2</td><td>Scratch/line on the glass/Polarizer</td><td>
<table>
<tr><td rowspan="2">Width (mm)</td><td rowspan="2">Length (mm</td><td colspan="2">Acceptable Number</td></tr>
<tr><td>Zone A,B</td><td>Zone C</td></tr>
<tr><td>W≤0.05</td><td>---</td><td>Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.05<W≤0.1</td><td>L≤5.0</td><td>3</td></tr>
<tr><td>W>0.1</td><td>---</td><td>0</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>3</td><td>Polarizer Bubble</td><td>
<table>
<tr><td rowspan="2">Average Diameter (mm)</td><td colspan="2">Acceptable Number</td></tr>
<tr><td>Zone A,B</td><td>Zone C</td></tr>
<tr><td>Φ≤0.2</td><td>Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.2<Φ≤0.5</td><td>3</td></tr>
<tr><td>Φ>0.5</td><td>0</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>4</td><td>Any Dirt & Scratch on Polarizer’s Protective Film</td><td>Ignore for not affect the polarizer.</td><td>Minor</td></tr>
<tr><td>5</td><td>Any Dirt on Cap Glass</td><td>Inside the Cap，Ignore the dirt without moving.</td><td>Minor</td></tr>
</table>

6	Glass Crack	 Propagation crack is not acceptable.	Major
7	Corner Chip	 t= Glass thickness Accept a≤2.0mm or b≤2.0mm, c≤t	Minor
8	Corner Chip on Cap Glass	 t= Glass thickness Accept a≤1.5mm or b≤1.5mm, c≤t	Minor
9	Chip on Contact Pad	 t= Glass thickness Accept a≤3.0mm or b≤0.8mm, c≤t (on the contact pin) a≤3.0mm or b≤2.0mm, c≤t (outside of the contact pin)	Minor
10	Chip on Face of Display	 t= Glass thickness Accept a≤1.5mm or b≤1.5mm, c≤t	Minor
11	Chip on Cap Glass	 t= Glass thickness Accept a≤2.0mm or b≤2.0mm, c≤t/2 a≤1.5mm or b≤1.5mm, t/2≤c≤t	Minor
12	Stain on Surface	Stain removable by soft cloth or air blow is acceptable.	Minor
13	TCP/FPC Damage	(1) Crack, deep scratch, deep hole and deep pressure mark on the TCP/FPC are not acceptable. (2) Terminal lead twisted or broken is not allowable. (3) Copper exposed is not allowed by naked eye inspection.	Minor
14	Dimension Unconformity	Checking by mechanical drawing.	Major

Ⅱ. Displaying Defects

<table>
<tr><th>NO.</th><th>Items</th><th>Criteria</th><th>Classification</th></tr>
<tr><td>1</td><td>Black/White spot
Dirty spot
Foreign matter</td><td>
<table>
<tr><td rowspan="2">Average Diameter (mm)</td><td colspan="2">Pieces Permitted</td></tr>
<tr><td>Zone A,B</td><td>Zone C</td></tr>
<tr><td>Φ≤0.10</td><td>Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.10＜Φ≤0.20</td><td>3</td></tr>
<tr><td>Φ＞0.20</td><td>0</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>2</td><td>No Display</td><td>Not allowable.</td><td>Major</td></tr>
<tr><td>3</td><td>Irregular Display</td><td>Not allowable.</td><td>Major</td></tr>
<tr><td>4</td><td>Missing Line
(row or column)</td><td>Not allowable.</td><td>Major</td></tr>
<tr><td>5</td><td>Abnormal Color</td><td>Refer to the SPEC.</td><td>Major</td></tr>
<tr><td>6</td><td>Luminance NG</td><td>Refer to the SPEC.</td><td>Major</td></tr>
</table>

15 Precautions for operation and Storage

15.1 Precautions for Operation

(1) Since OLED panel is made of glass, do not apply any mechanical shock or impact or excessive force to it when installing the OLED module. Any strong mechanical impact due to falling dropping etc. may cause damage (breakage or cracking).

(2) The polarizer on the OLED surface is made of soft material and is easily scratched. Please take most care when handing. When the surface of the polarizer of OLED Module is contaminated, please wipe it off gently by using moisten soft cloth with isopropyl alcohol, do not use water, ketone or aromatics. If there is saliva or water on the OLED surface, please wipe it off immediately.

(3) When handling OLED module, please be sure that the body and the tools are properly grounded. And do not touch I/O pins with bare hands or contaminate I/O pins, it will cause disconnection or defective insulation of terminals.

(4) Do not attempt to disassemble or process the OLED module.

(5) OLED module should be used under recommended operating conditions shown in the specification. Since the higher voltage leads to the shorter lifetime, be sure to use the specified operating voltage.

(6) Foggy dew, moisture condensation or water droplets deposited on surface and contact terminals will cause polarizer stain or damage, the deteriorated display quality and electrochemical reaction then leads to shorter life time and permanent damage to the module probably. Please pay attention to the environmental temperature and humidity.

(7) An afterimage is created by the difference in brightness between unused dot and the fixed dot, according to the decrease of brightness of the emitting time. Therefore, to avoid having an afterimage, the full set should be thoroughly used instead of using a fixed dot. When the fixed dot emits, an afterimage can be created.

(8) Flicker could be come out at full on display. And it disappears when frame frequency increase, but brightness decreases too.

15.2 Soldering

(1) Soldering should be performed only on the I/O terminals.

(2) Use soldering irons with proper grounding and no leakage.

(3) Iron:The temperature setting of electric iron is 350℃, but we suggest that during soldering, the tem perature of iron tip should be no higher than 330℃ and soldering be finished within 3~4 seconds.

15.3 Precautions for Storage

(1) Please store OLED module in a dark place. Avoid exposure to sunlight, the light of fluorescent lamp or any ultraviolet ray.

(2) Keep the environment temperature between 10℃ and 35℃ and the relative humidity less than 70%. Avoid high temperature and high humidity.

(3) Keep the OLED modules stored in the container when shipped from supplier before using them is recommended.

(4) Do not leave any article on the OLED module surface for an extended period of time.

15.4 Warranty period

QingYue warrants for a period of 12 months from the shipping date when stored or used under normal condition. In addition to failure and quality problems caused by man-made damage and force majeure, we promise to provide maintenance and replacement free of charge during the warranty period. If the warranty period has been exceeded, we need to collect the staff's travel expenses, materials and other related costs.